



Area, Delay, Power, and Cost Trends for Structured ASICs

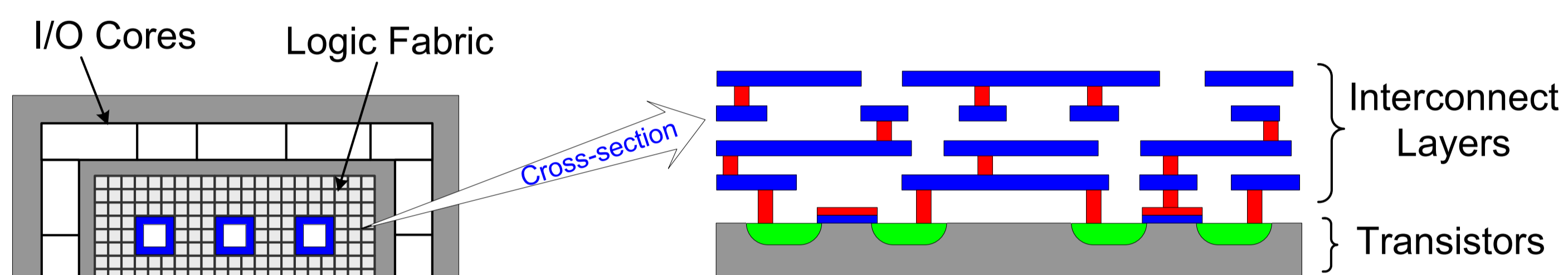
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1. Motivation

- ◆ Current IC Design Issues
 - ◆ Enormous Design Effort
 - ◆ Huge NRE Costs
- ◆ Many ICs Still Manufactured with Old Processes
- ◆ FPGAs Not Always Suitable
 - ◆ Low Power, Hand-held Devices
 - ◆ Platform-based Designs, Analog or Hard IP
- ◆ Structured ASICs Promising, Little Research
 - ◆ Research Tools Needed, e.g. VPR for SAs

2. Structured ASICs

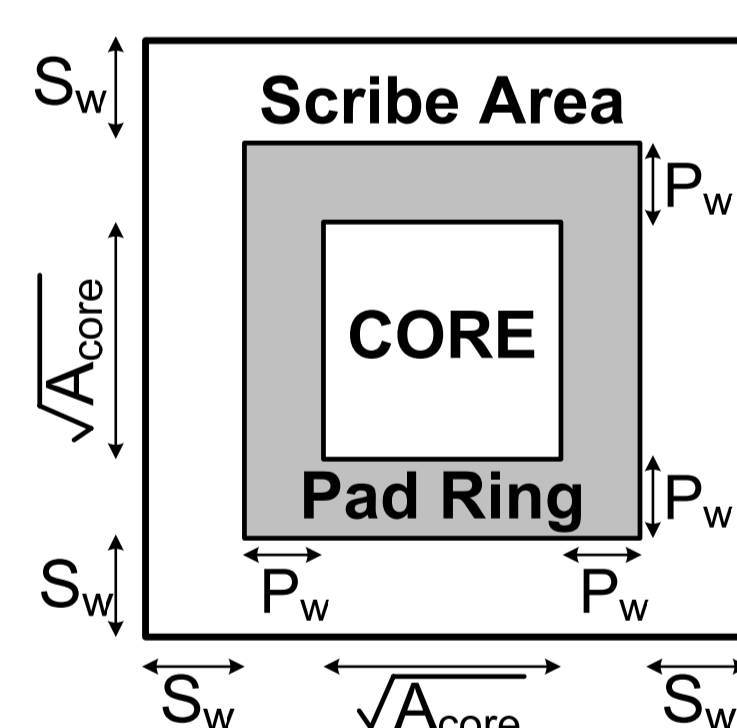
- ◆ ASIC-like Efficiency with FPGA-like Configurability
 - ◆ Metal + Via Programmable (MPSA), FPT2009 (this work)
 - ◆ Via-only Programmable (VPSA), FPGA2010 (coming soon)



- **Standard-cell ASIC aka Cell-based IC**
 - All mask layers are customized for a design
- **FPGA**
 - All mask layers are prefabricated, shared by all designs
 - User design obtained by programming memory cells
- **Structured ASIC**
 - Most layers are prefabricated, shared by all designs
 - A few mask layers are customized for a design
 - User design fine-tuned by programming memory cells (optional)

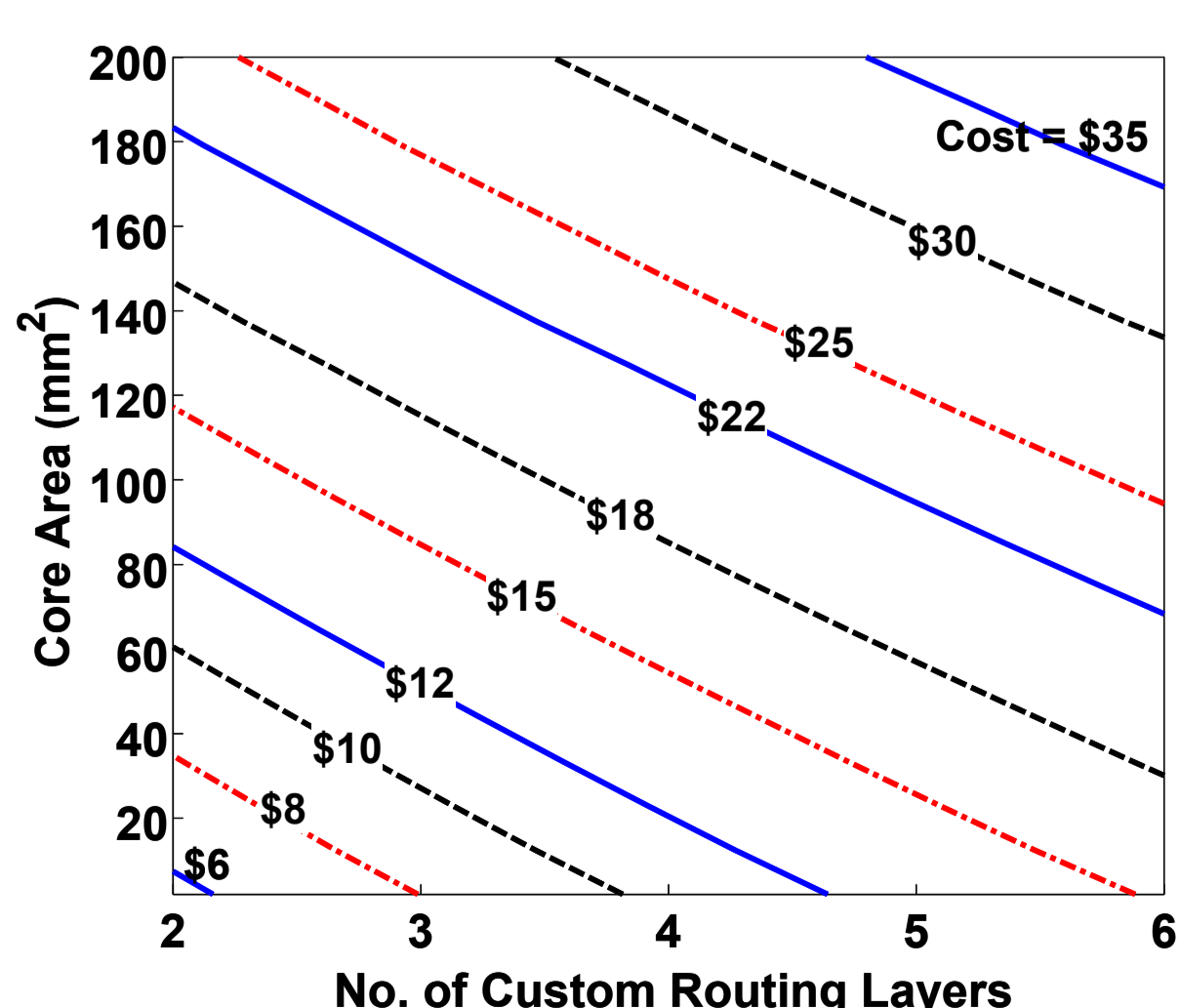
3. MPSA Die Cost

- ◆ Key Variables
 - ◆ Die Area and Yield: N_{gdpw} (good dies per wafer)
 - ◆ Custom Routing Layers: N_{rl}
- ◆ Key Fixed Parameters
 - ◆ Manufacturing Volume: V_{total}, V_{design}
 - ◆ Wafer Processing Costs: C_{wpm} (\$ per mask)
 - ◆ Mask Costs: C_{lower}, C_{upper} (\$ per mask)
 - ◆ Mask Layers: N_{lower}, N_{upper}



$$Cost_{die} = \frac{K_0}{N_{gdpw}} + N_{rl} \left(\frac{K_1}{N_{gdpw}} + K_2 \right) + K_3$$

$C_{wpm}(N_{lower} + N_{upper}) \sim \4000
 $N_{mprl} C_{wpm} \sim \$440$
 $\frac{C_{lower} N_{lower} + C_{upper} N_{upper}}{V_{total}} \sim \0.99
 $\frac{N_s C_{upper} N_{mprl}}{V_{design}} \sim \1.44

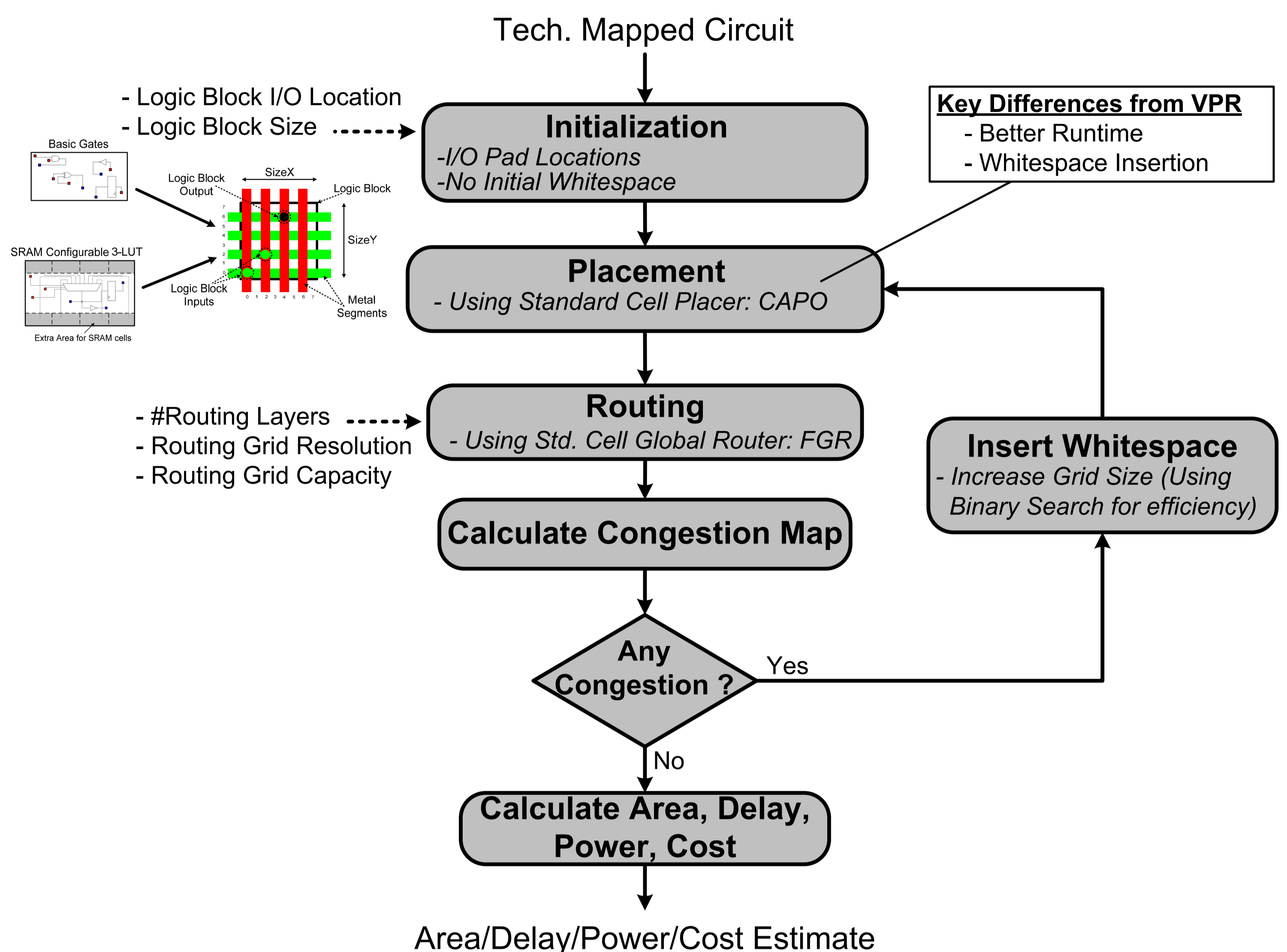


Key Assumptions

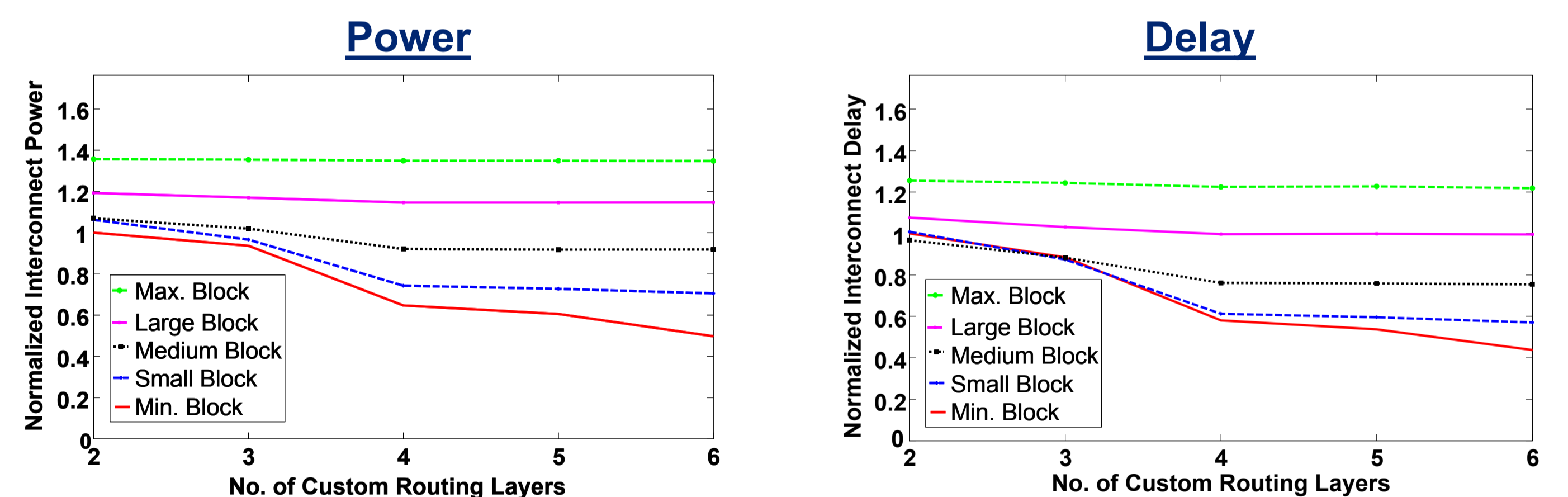
- 45nm Maskset Cost: \$2.5M
- Total Volume: 2 M
- Per-design Volume: 100k
- Design Re-spins: 1

Chips can be 2-4x Bigger using only 2 Custom Layers

4. CAD Flow

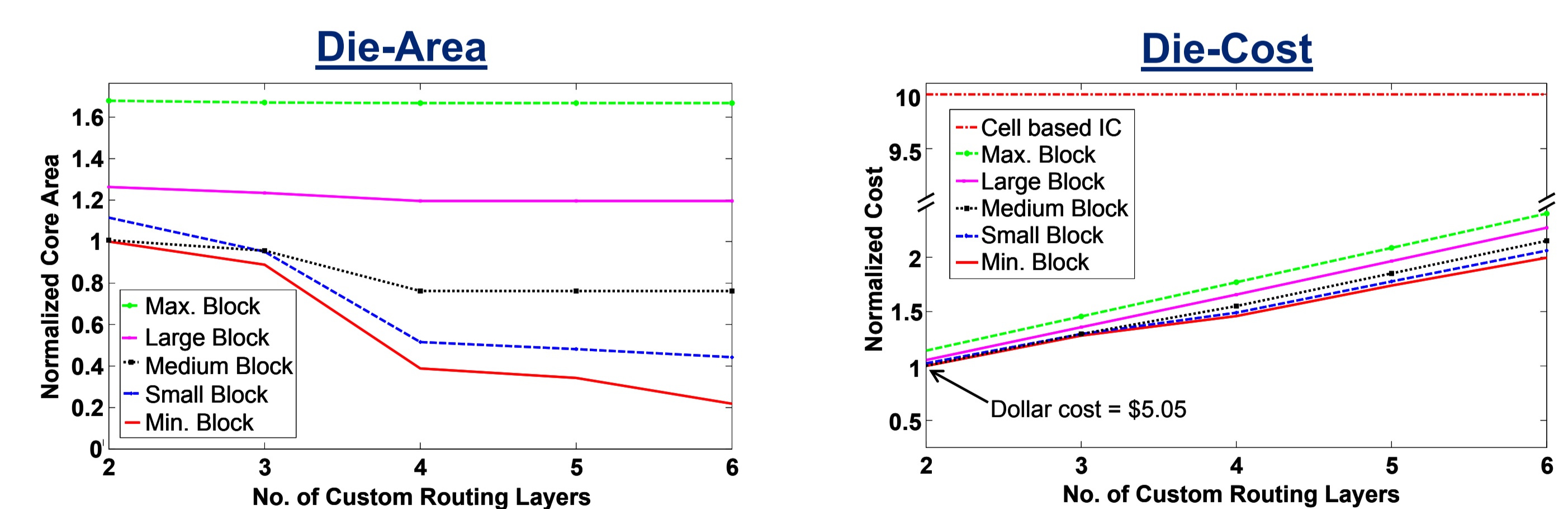


5. Power and Delay Trends



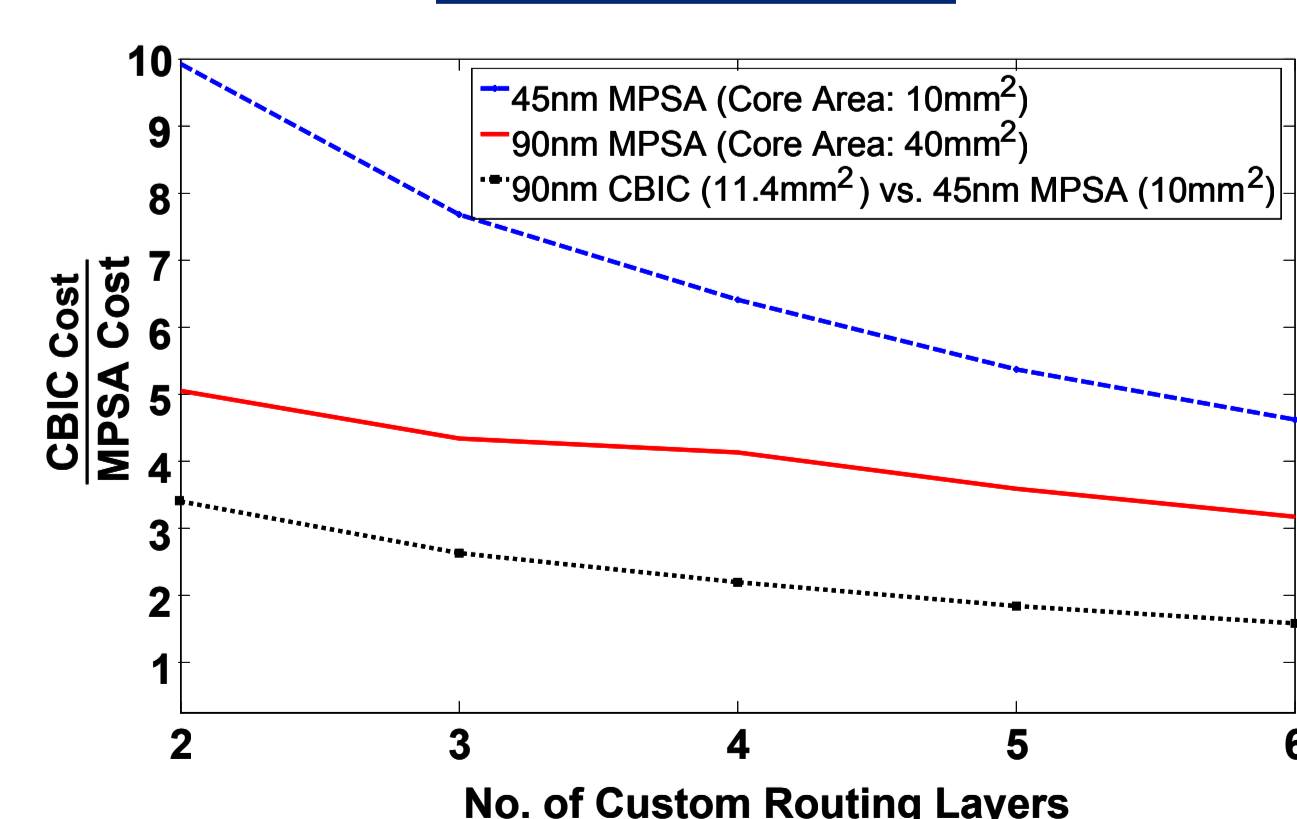
Sparse Layouts: 2 Custom Layers are Good Enough
Dense Layouts: 4 Custom Layers are Good Enough

6. Area and Cost Trends



Area Savings of More Layers != Cost Savings

MPSA vs CBIC



ASICs 2-10x More Expensive than Structured ASICs